



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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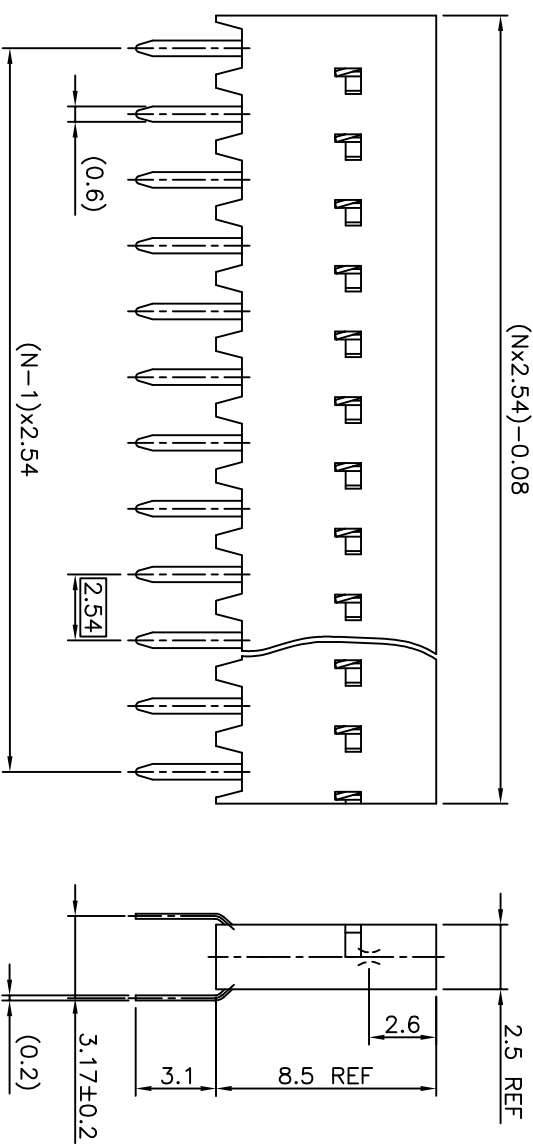
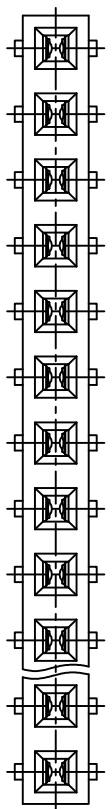
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PRODUCT NUMBER
71920-XXXXLE

- ROHS COMPATIBLE, SEE NOTE 5
- OPTIONAL LETTER
- H: HIGH TEMPERATURE PRODUCT.
- NUMBER OF POSITIONS: 02 TO 50.
- PLATING CODE
- 3 = 0.76µm GOLD ON CONTACT AREA.
- 2µm MIN MATTE TIN ON TAIL.
- 4 = 2µm MIN MATTE TIN FULL PLATED
- 1.27µm Ni MIN UNDERPLATING



NOTES:

- 1 - HOUSING MAT'L: THERMOPLASTIC GLASS FILLED FLAME RETARDANT PER UL 94 V-0
LOW TEMPERATURE: COLOR BLUE
HIGH TEMPERATURE: COLOR GREY.
- 2 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 - 2 UP TO 4 POSITIONS PRODUCT PACKED IN PLASTIC BOX.
- 5 UP TO 50 POSITIONS PRODUCT PACKED IN TUBE.
- 4 - TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS
EXAMPLE: 8 POS: (Nx2.54)-0.08=20.24 mm
- 5 - ROHS COMPATIBLE PRODUCT SPECIFICATIONS

d - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

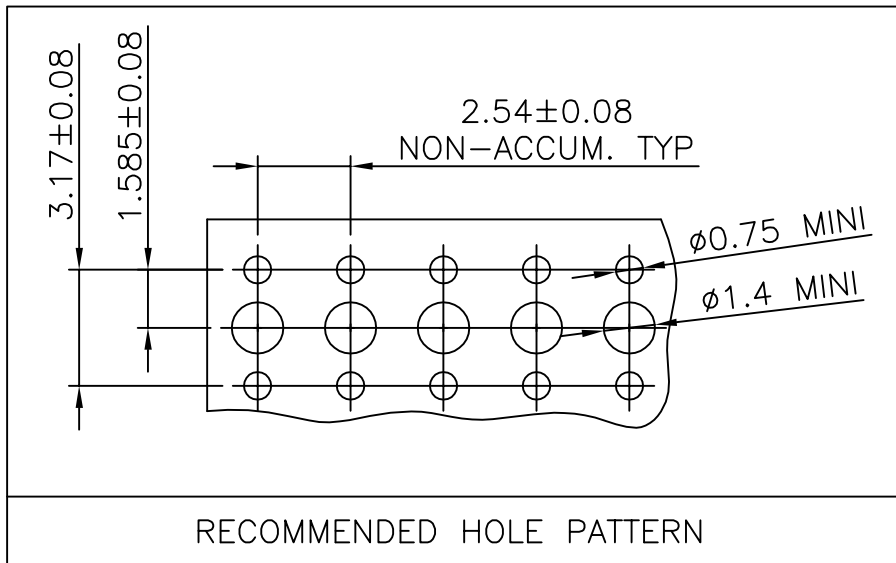
b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELING:

- MEETS PACKAGING SPECS AS PER GS-14-920
- LEGAL STATEMENT: SEE GS-47-0004

mat'l. code		SEE NOTES		surface	tolerance	projection	product family
ltr	ecn no	dr	date	ISO 1302	ISO 406	ISO 1101	DUBOX
L	F04-034	DLE	04.09.23	tolerances unless otherwise specified	±0.3	mm	BtB RECEPT.
M	F05-023	DLE	05.08.08	linear		mm	VERT SR TMT
N	F06-020	DLE	06.06.19	#2		scale 5:1	
P	F07-010	DLE	07.01.16	DR	D LEGRAND		dwg no
R	B-19123	LMU	14.10.21	lengr	P NIZZI		71920
K	F03-028	DLE	03.10.14	qppd	P NZ		sheet 1 of 2
sheet	revision	R	D				A3
index	sheet	1	2				Drwng



mat'l. code SEE SHEET 1				surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family DUBOX				
ltr	ecn no	dr	date	tolerances unless otherwise specified		angles		mm ←→		title BtB RECEPT. VERT SR TMT				
A	F04-0347	DLE	04.09.23	linear	±0.3		scale 5:1				dwg no		sheet 2 of -	size
B	F05-0230	DLE	05.08.08		±2'		71920				A4			
C	F06-0204	DLE	06.06.19		±2'		CUSTOMER				Drawing			
D	F07-0109	DLE	07.01.16	dr	D LEGRAND	04.09.23								
				enr	P NIZZI	04.09.23								
				chr	D LE	04.09.23								
				appd	P NZ	04.09.23								
sheet index	revision sheet													